

GPO 11733 18

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Edward A. Schrock et al.

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

Docket No.: 303.527US2

Filed: August 29, 2000

Examiner: John J. Gallagher

Serial No.: 09/649,827

Due Date: December 24, 2002

Group Art Unit: 1733

Commissioner for Patents
Washington, D.C. 20231

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We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response (8 Pages).
- ☒ A Supplemental Information Disclosure Statement (1 pg.), Form 1449 (1 pg.), and copies of 2 cited references.
- ☒ A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).
- ☒ Clean Version of Pending Claims (7 pgs.).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Andrew R. Peret
Atty: Andrew R. Peret
Reg. No. 41,246

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 18th day of October, 2002.

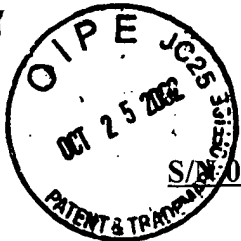
Name Amy Moriarty

Signature Amy Moriarty

Customer Number 21186

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)



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#17/F

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

✓ 20E

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10/31/02

Applicant has reviewed the Office Action mailed on September 24, 2002 and please amend the above-identified patent application as follows.

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IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claim 61 and amendment of previously pending claims 34-39, 43, 44, 48, 51, 62 and 63. The specific amendments to individual claims are detailed in the following marked up set of claims.

Please cancel claim 61 and amend the following claims.

34.) (Twice Amended) A method of attaching a semiconductor die to an organic support structure, comprising:

selecting a two-sided adhesive tape having a polyimide carrier layer positioned between a first adhesive layer and a second adhesive layer; the first and second adhesive layers each comprising a hybrid material of thermoplastic and thermosetting adhesive [at least one adhesive, wherein the adhesive tape has a low lamination temperature];

affixing [a first side of the two-sided adhesive tape] the first adhesive layer to a surface of the organic support structure; and

affixing a face of the semiconductor die to [a second side] the second adhesive layer of the adhesive tape.